

VERTEXING AND TRACKING

Joel Goldstein
SiD Collaboration Meeting
LCWS_{I5}

Outline

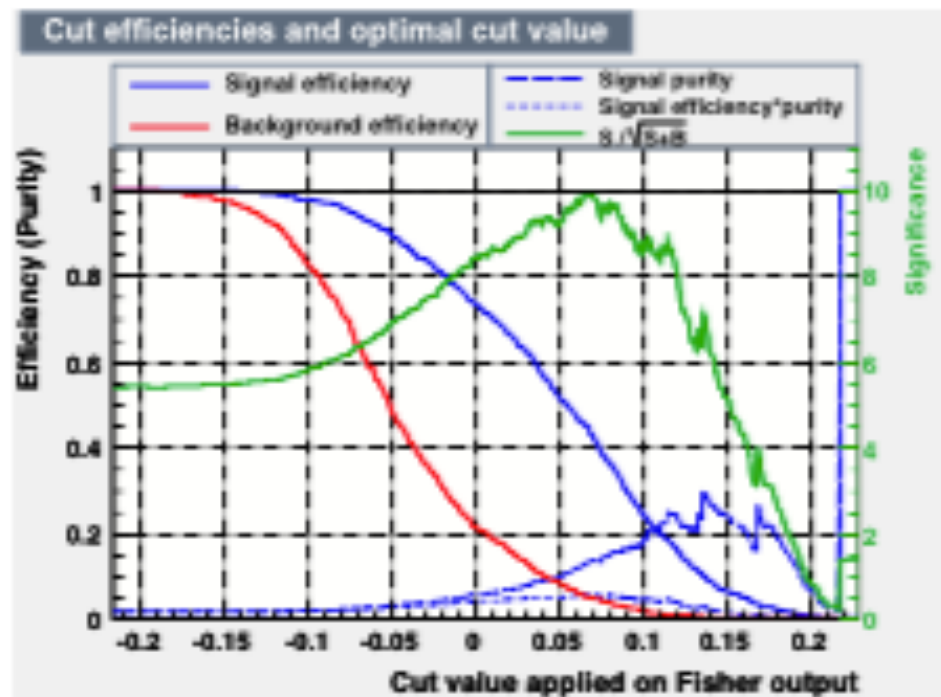
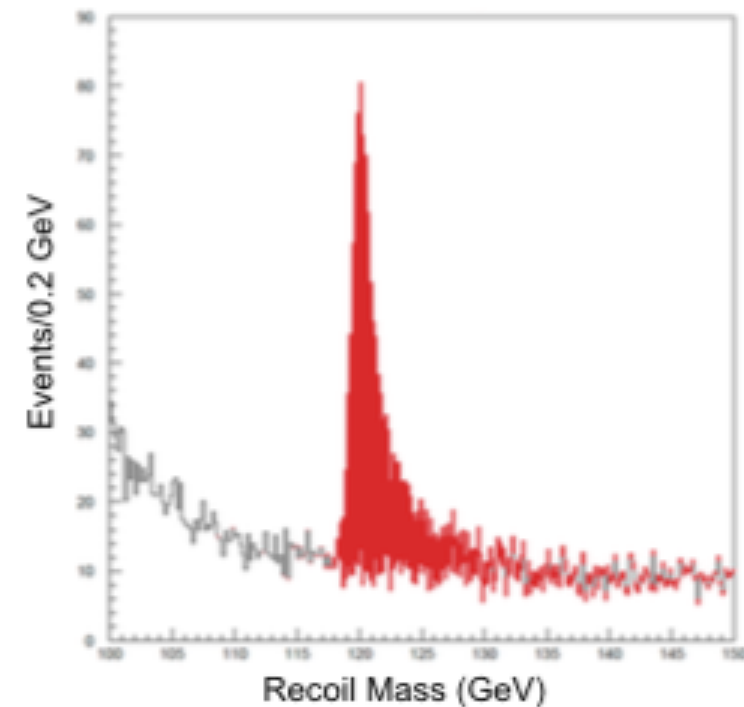


1. Overview of SiD vertexing and tracking
2. Status of vertexing R&D
3. Status of tracking R&D
 - *Progress within SiD community*
 - *Relevant developments elsewhere*
4. Summary

Physics Drivers



- * Higgs recoil from $Z \rightarrow \mu\mu$
- * $\Delta p/p^2 \leq 5 \times 10^{-5} / \text{GeV}$
- * Flavour tagging
- * Impact parameter resolution
 $5 \oplus 10/p \sin^{3/2} \theta \mu\text{m}$

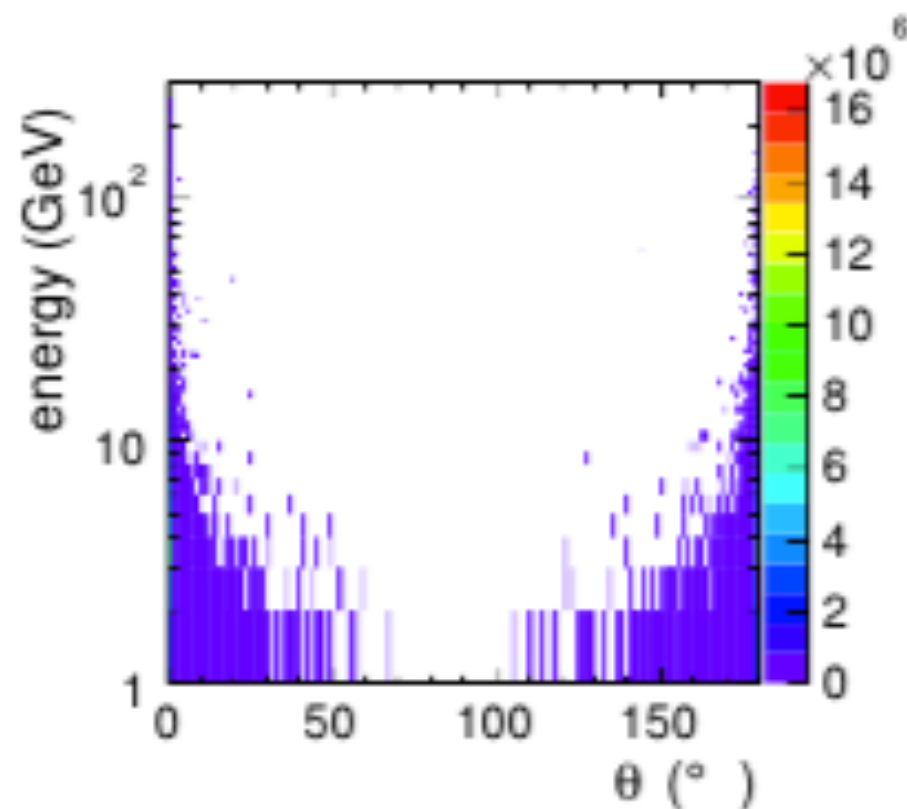


- * Low material in inner detector
- * Minimal services
- * **Low power**

Constraints

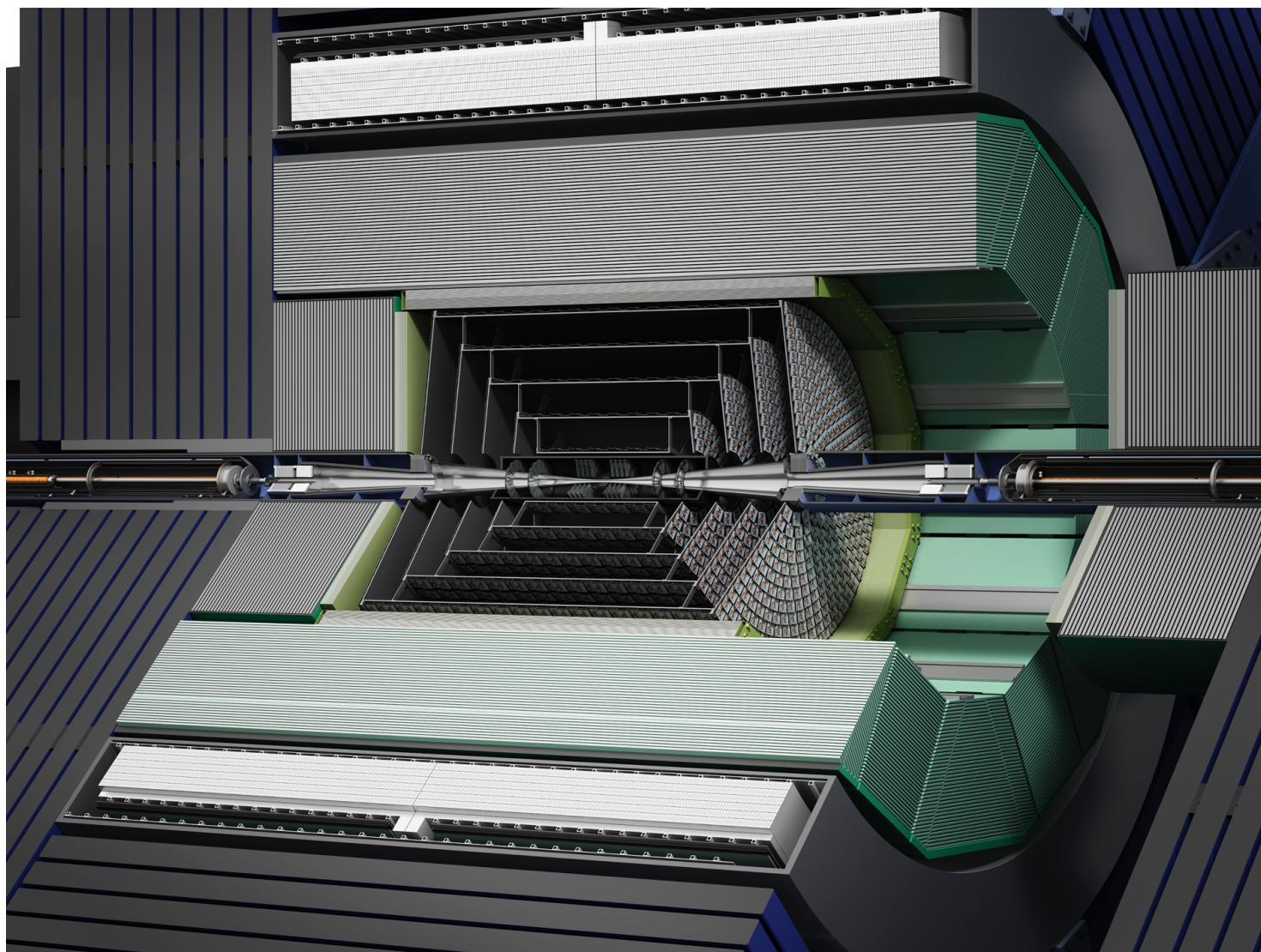


- * Beam structure:
 - * 1312 bunches
 - * 554 ns spacing
 - * 5 Hz repetition



- * Backgrounds
 - * Beamstrahlung
 - * Low- p_T e^+e^- pairs
 - * $\sim 10^5$ pairs per bunch
 - * $\gamma\gamma$ collisions
 - * ~ 1 hadronic events per bunch
- * Speed/timing, granularity
- * **Tension with low power**

Baseline

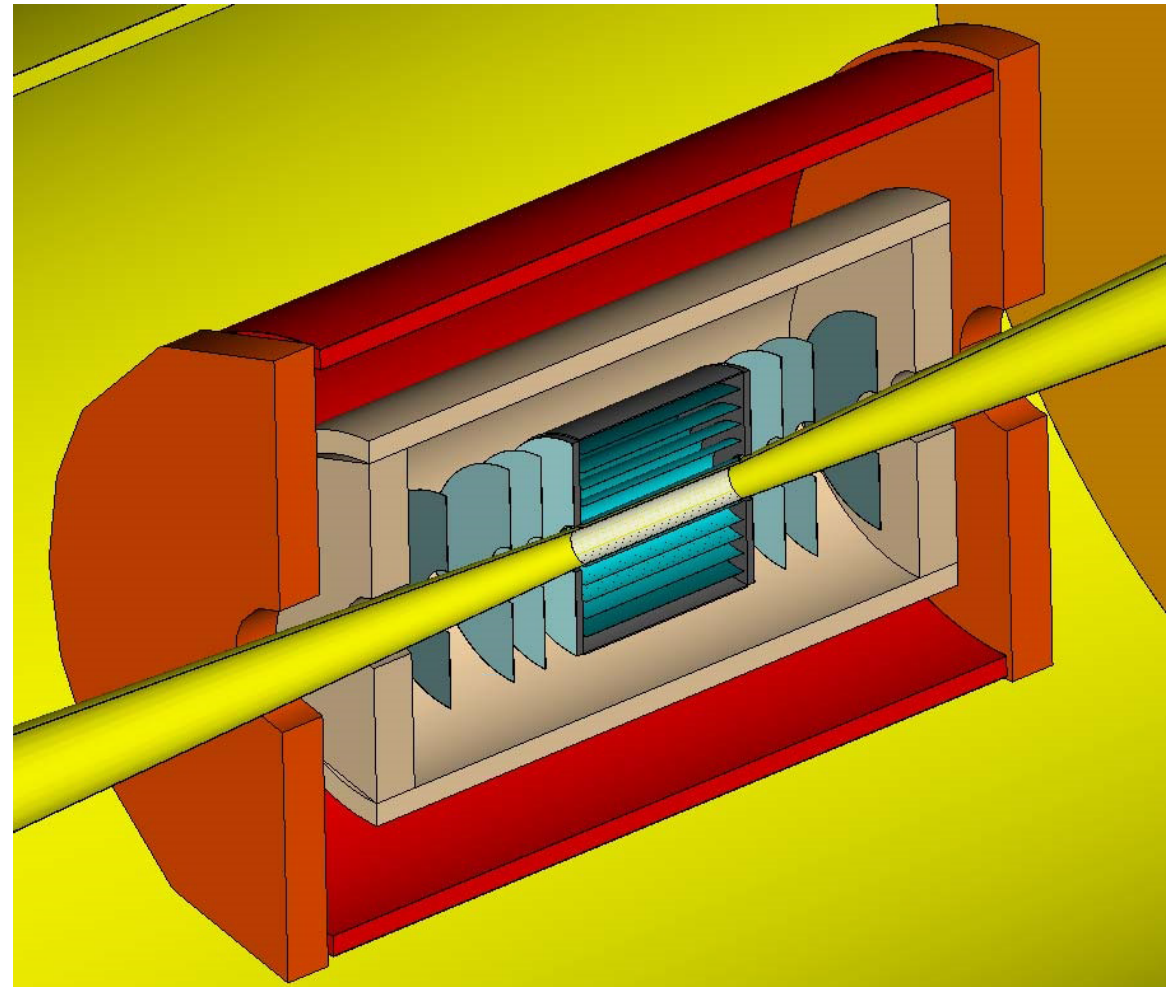


- * Low mass
- * 10-20% X_0
- * Gas cooled
- * Bunch-X timing

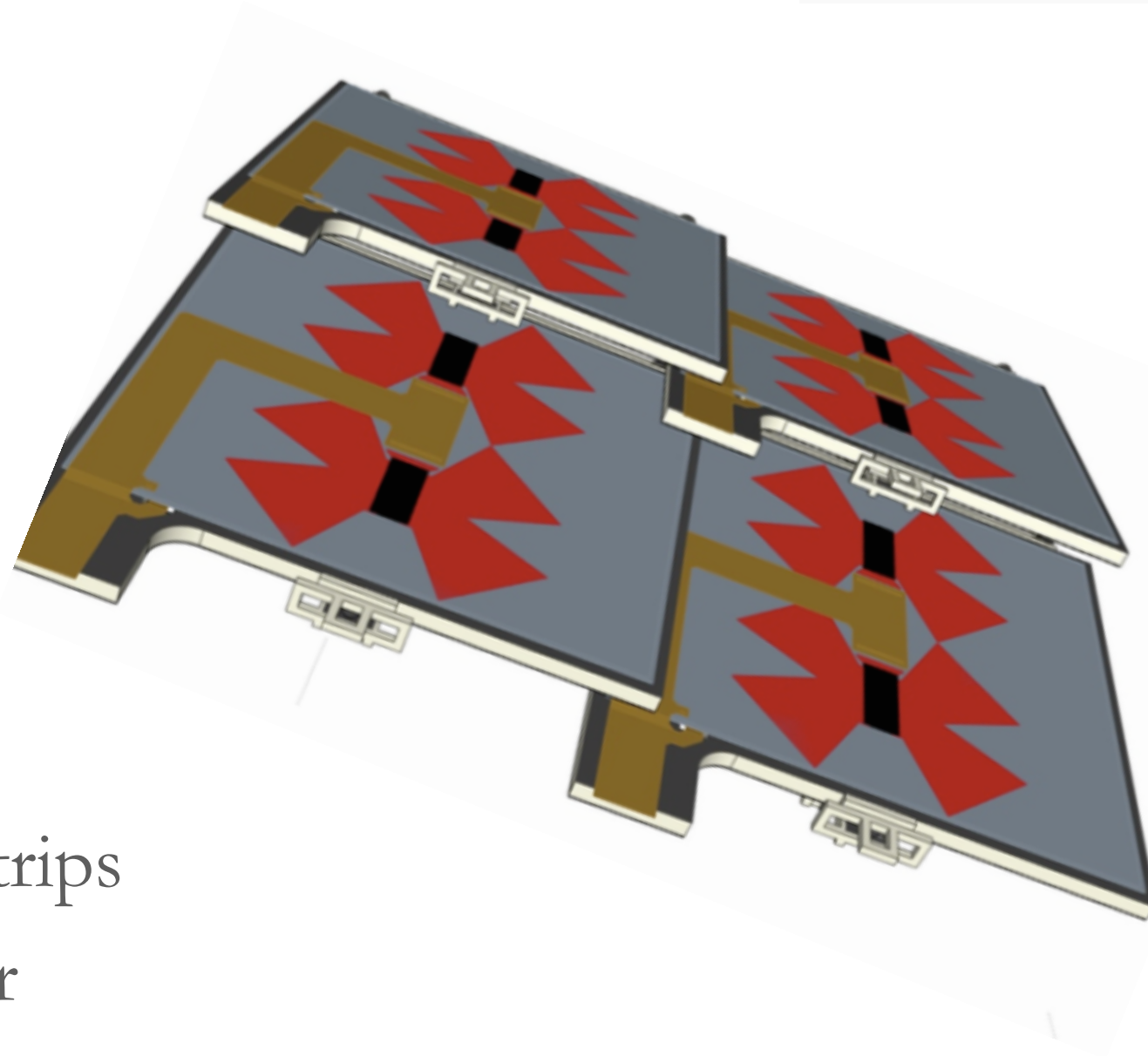
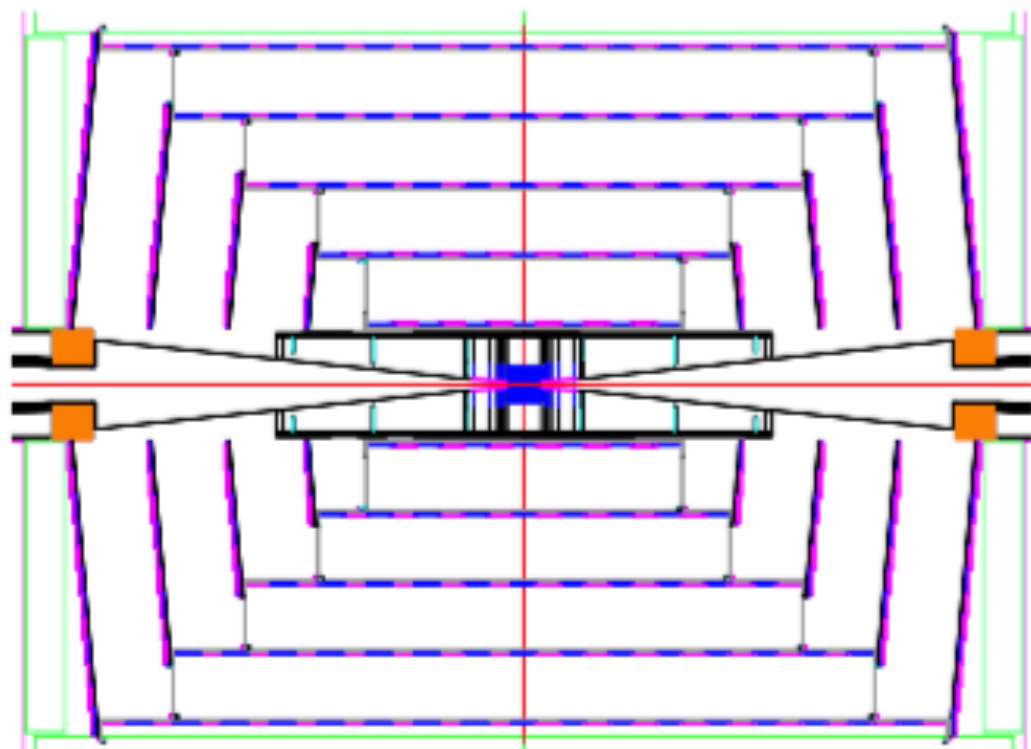
Vertex Detector



- * “Short” barrel
 - * 5 layers
 - * 15 cm long
- * Endcaps
 - * 4 disks each
- * $20\mu\text{m} \times 20\mu\text{m}$ pixels
- * Single-bunch timing
- * **Various technologies under consideration**



Tracker



- * 5 layers of silicon strips
- * $\sim 1\%$ X_0 per layer
- * 50 μm readout pitch with intermediate strips
- * KPix frontend ASIC

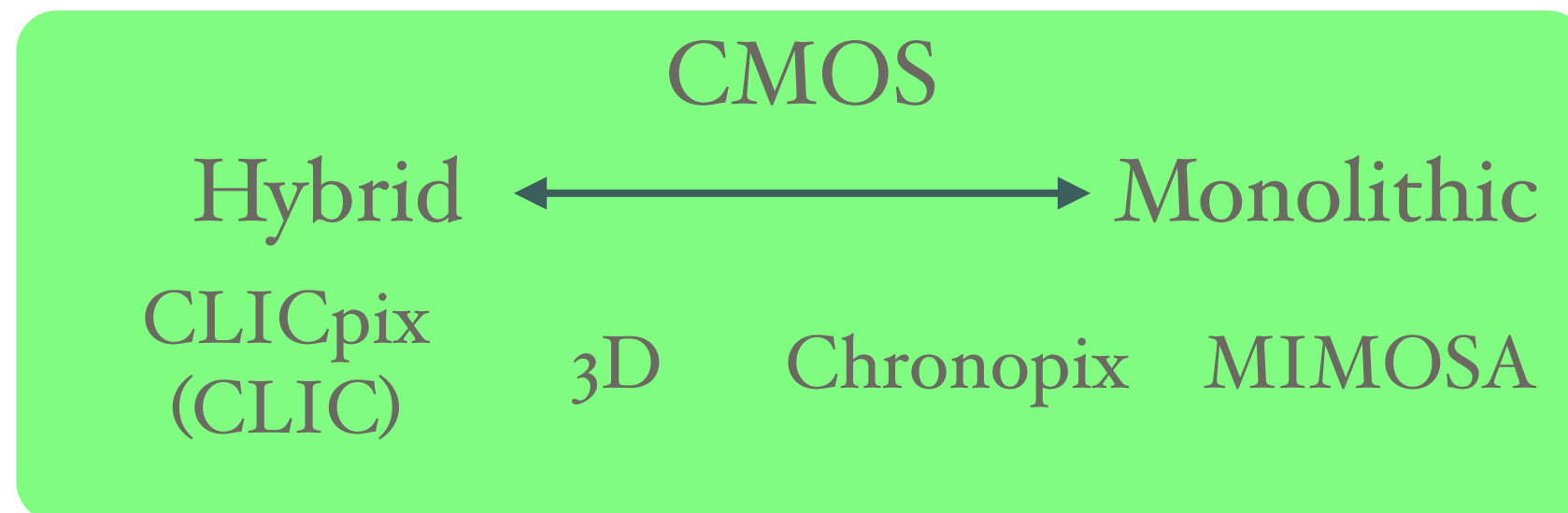
Vertex Sensors



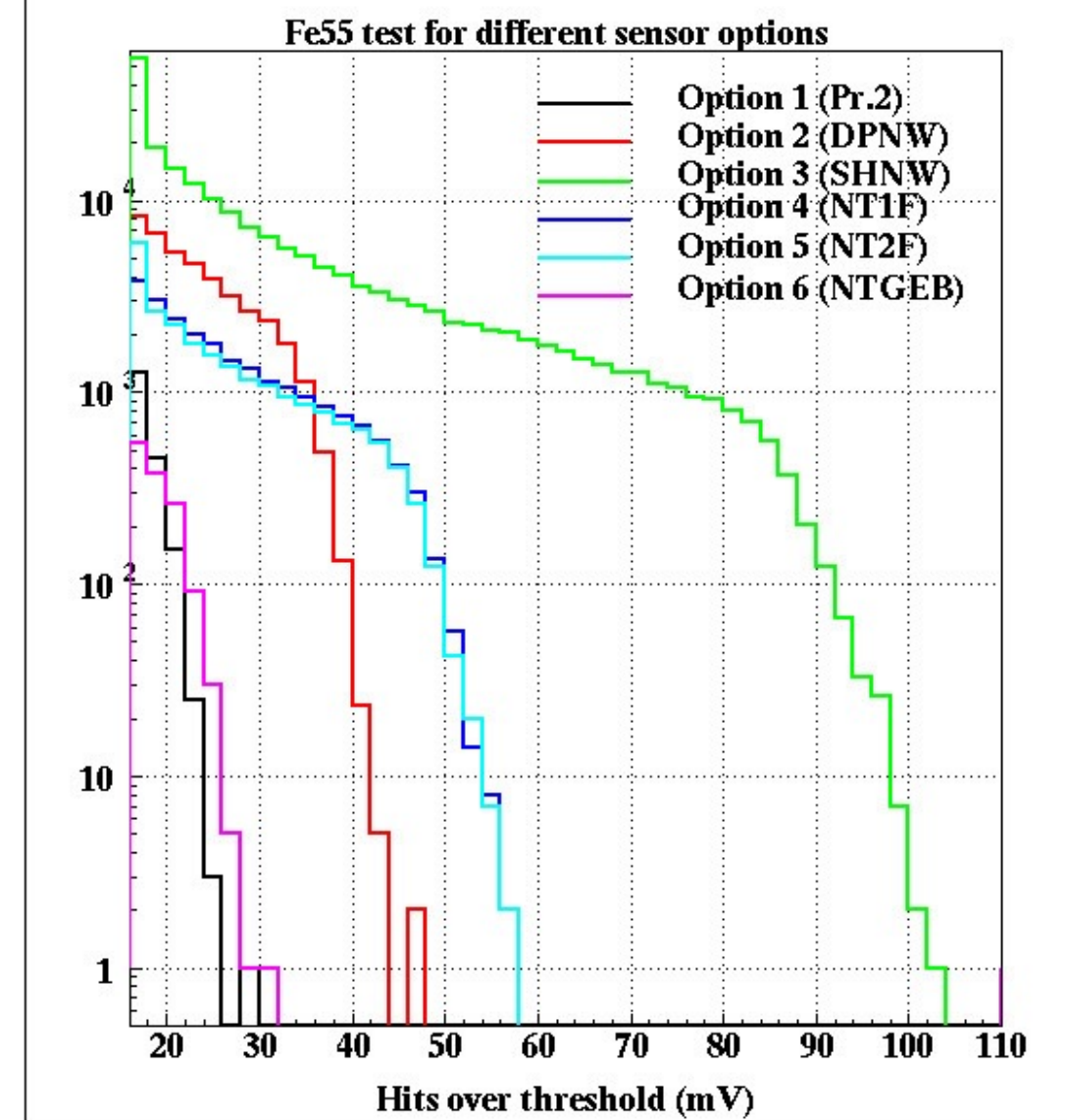
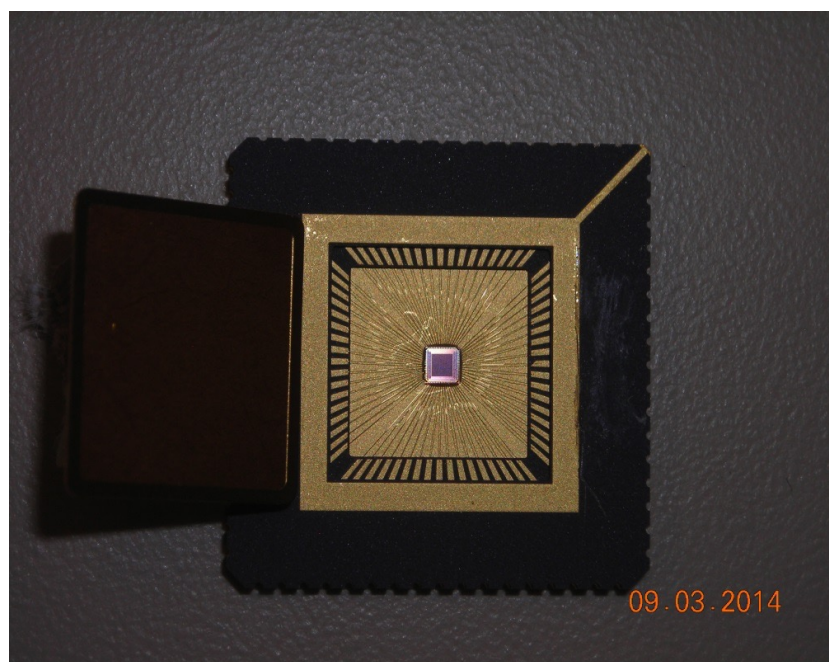
- * Many pixel R&D programmes active at some level
- * $3\mu\text{m}$ resolution with fast timing
- * Pulse power to reduce heat load

CCD
Fine Pitch (ILD)

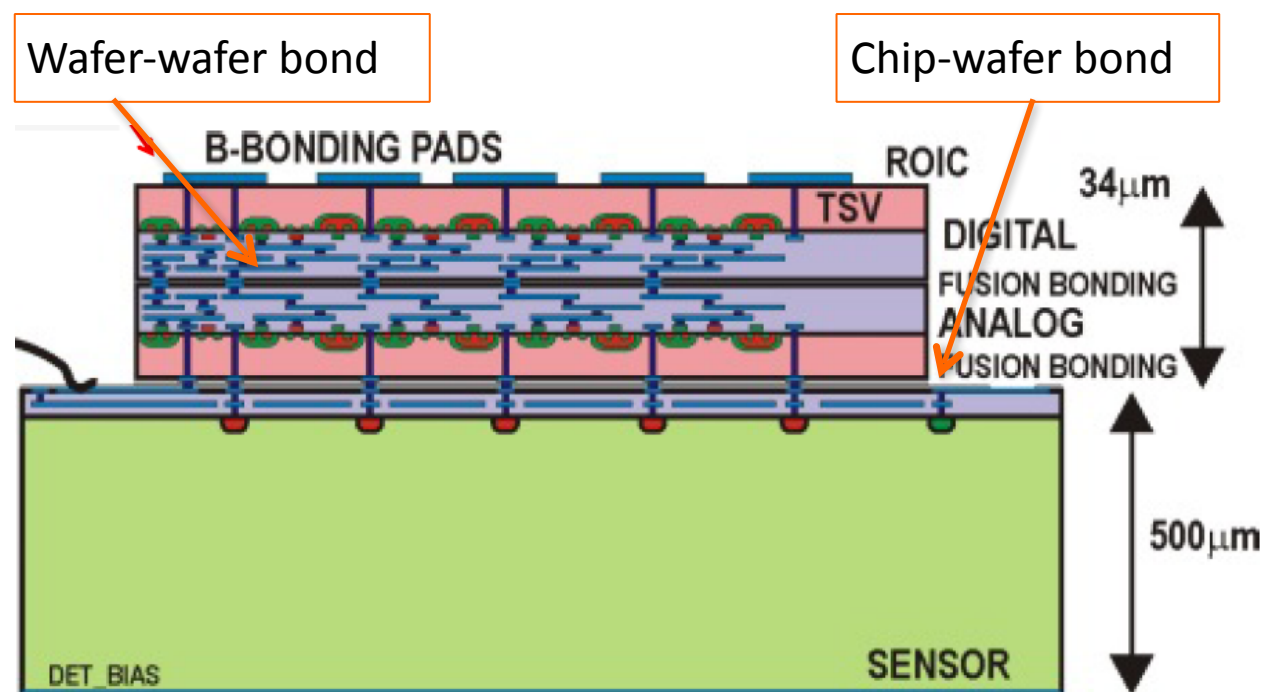
DepFET
(ILD)



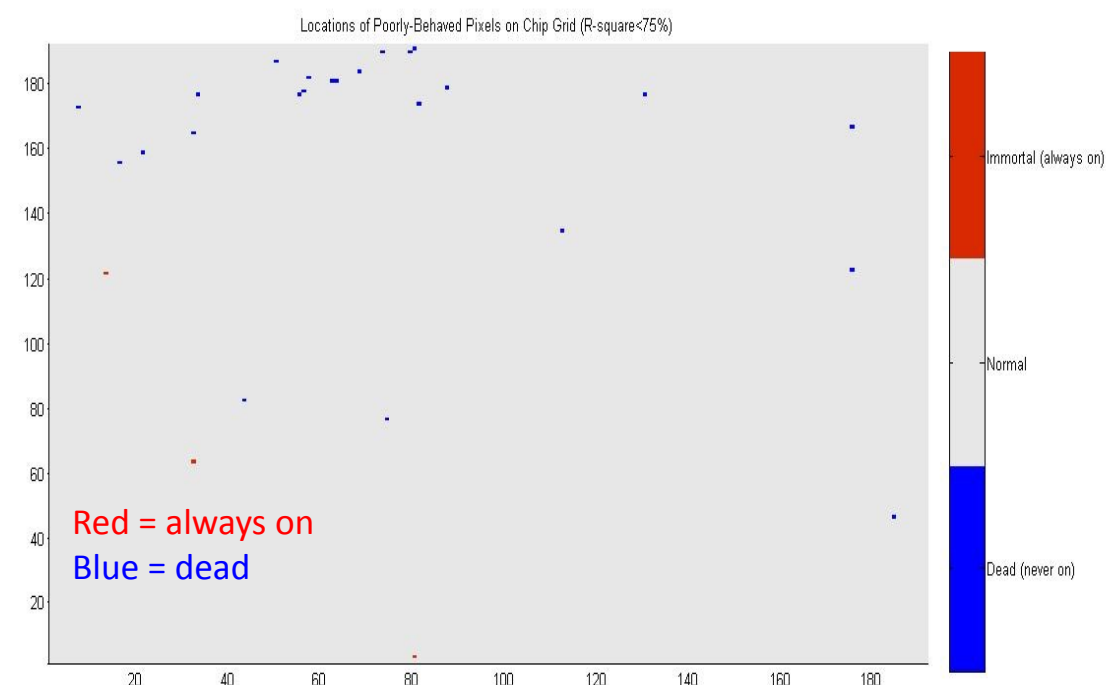
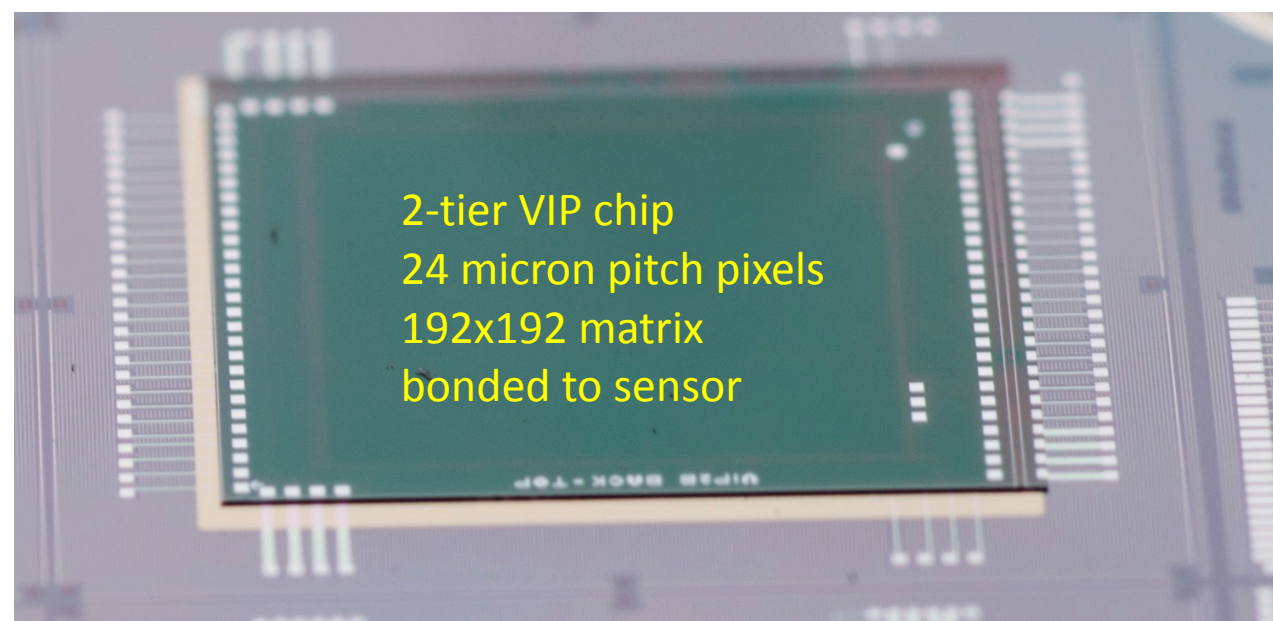
- * 3rd generation prototype
- * $25\mu\text{m} \times 25\mu\text{m}$ pixels in 90nm CMOS
- * Bunch-by-bunch time-stamping
- * Noise and cross-talk controlled



3D Project



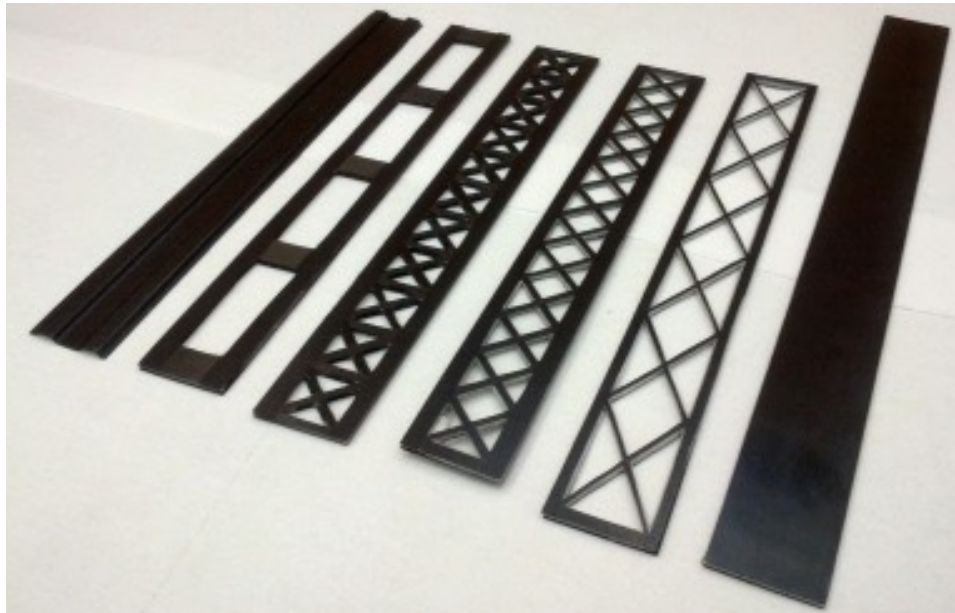
- * Vertical integration using TSVs
- * Three layers bonded
- * Production could be commercialised



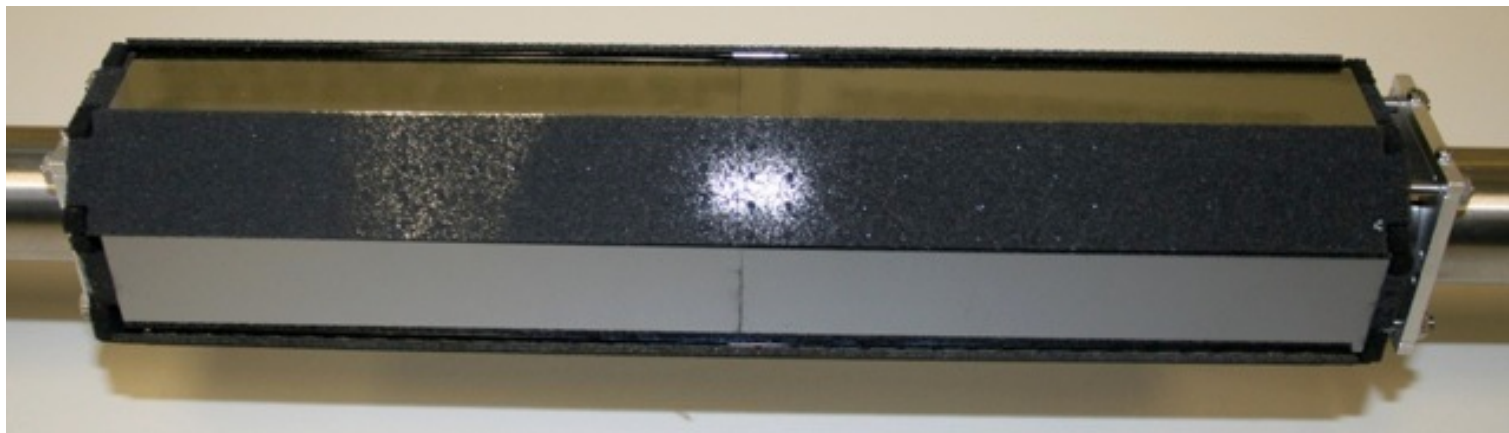
Mechanics



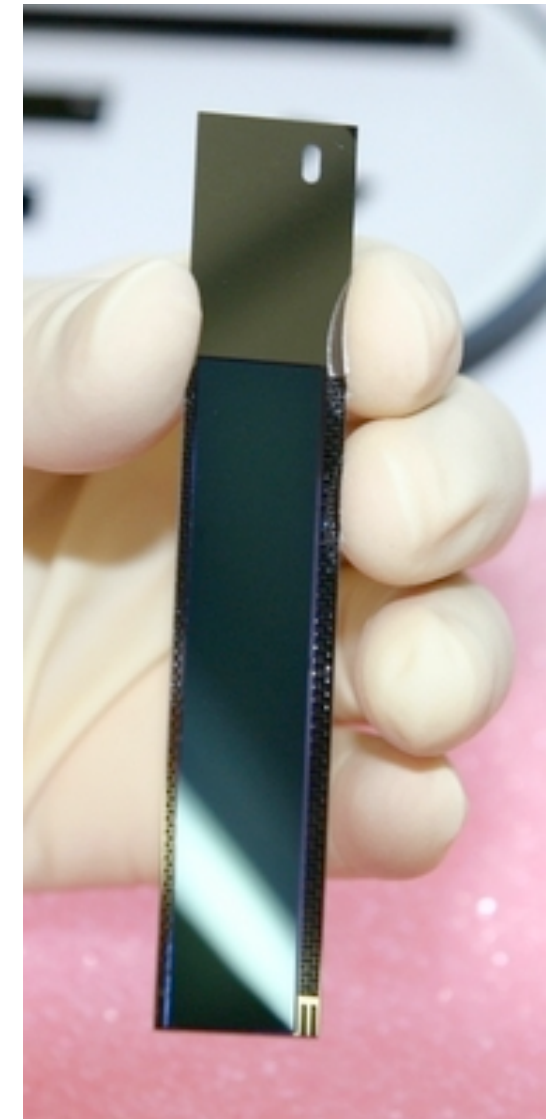
* Aiming for 0.1-0.3% X_0 per layer



Advanced Carbon
Fibre (CLIC)

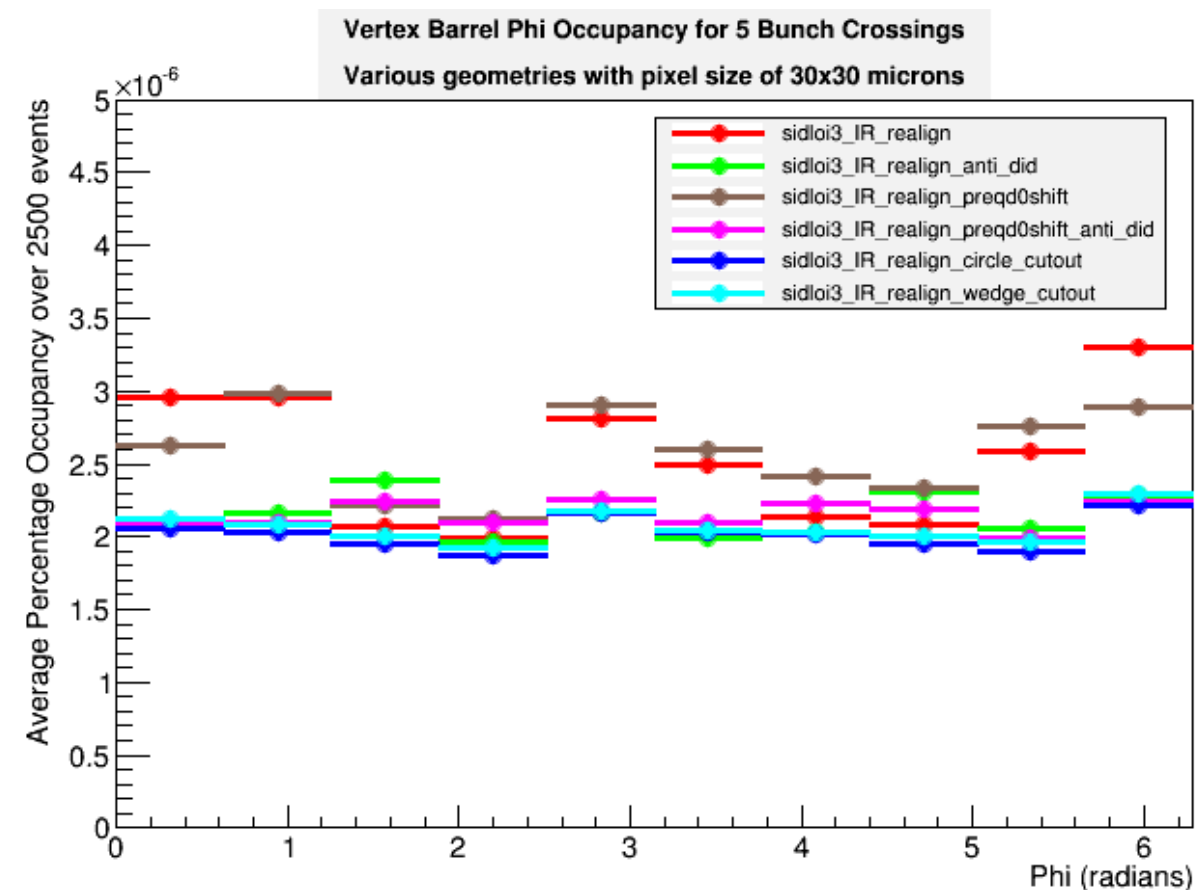
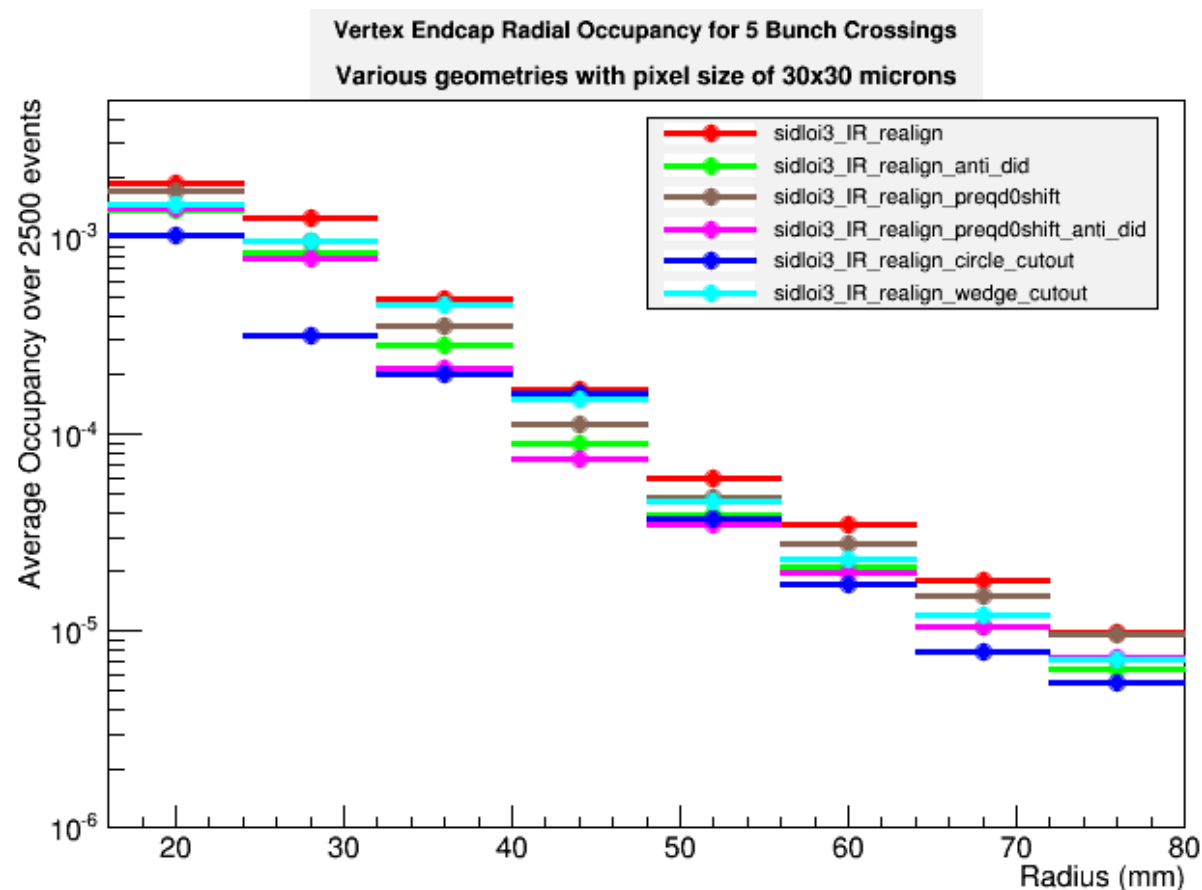


Ceramic Foam (LowMass/PLUME)



Silicon Only
(DepFET/SiD)

- * Ongoing studies
- * Looking at effect of configuration changes
- * See talks tomorrow and Friday



Pixel Tracker



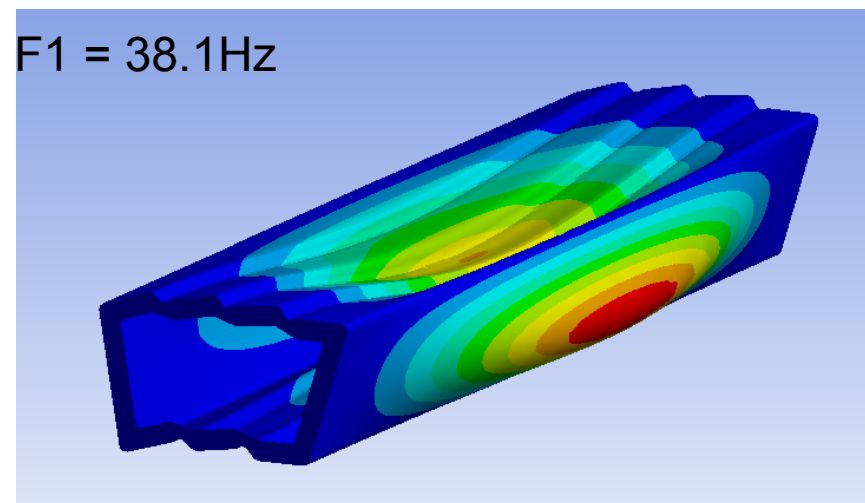
- * Obvious advantages for pixelating tracker
 - * More robust pattern recognition
 - * Thinner sensors so reduced mass
 - * Standard CMOS so may be cheaper
- * **Can power consumption be kept down....???**
- * Various groups now working on this
 - * Overlap with LHC upgrades
- * **Needs detailed simulation**



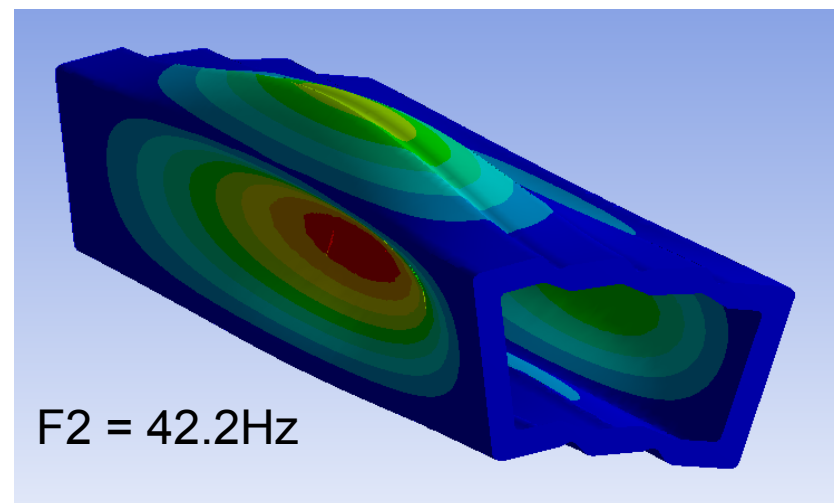
UK Pixel Tracker



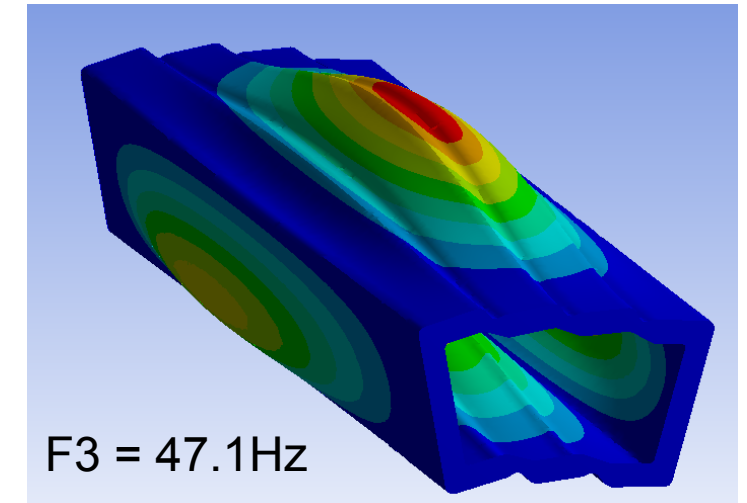
- * Simulations
 - * Required spatial and temporal granularity
- * Mechanics
 - * Can sufficient gas flow be guaranteed?
 - * FEAs of box channel structure
 - * May be able to prototype...?



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Summary



- * SiD baseline vertex and silicon tracker design
 - * Low mass, single bunch timing
- * Steady progress towards vertex technology
- * CMOS pixel tracker real possibility
 - * Hope to validate soon